



conga-HPC/EVAL-Server



COM+HPC™

- Evaluation Carrier Board for COM-HPC Server Type Modules
- Routing of the entire signals provided by COM-HPC Module Base Specification R1.0 to standard interface connectors

Form Factor

Board Type

Internal Connectors and Features

Extended ATX

Evaluation Carrier Board for COM-HPC Server Type Modules (Sizes D and E)

2x PCIe x16 connector
 2x PCIe x8 connector
 3x PCIe x4 connector
 2x dual USB 2.0 header
 M.2 Key M 2230 / 2242 / 2260 / 2280 / 22110
 8x Ethernet KR interfaces connector
 2x SATA
 SATA Power
 2x UART DB9 from module
 1x UART DB9 from BMC
 1x UART DB9 for BMC console
 GP SPI header
 I2C header
 SMB header
 eSPI header
 SPI socket
 GPIO header
 Feature header
 3x Fan

External Connectors

4x USB3.2 Gen 1 Type A
 DP through BMC
 10GbE RJ45 through module
 GbE RJ45 through ASPEED AST2600

Postcode

4x 7-Segment Postcode LEDs connected to PD I2C

Power Input

ATX connector, 12V/GND banana jacks

Operating Temperature

Operating Temp.: -40°C ... +85°C Storage Temp.: -40°C ... +85°C

Humidity

Operating Hum.: 10% ... 90% r. H. non cond. Storage Hum.: 5% ... 95% r. H. non cond.

Size

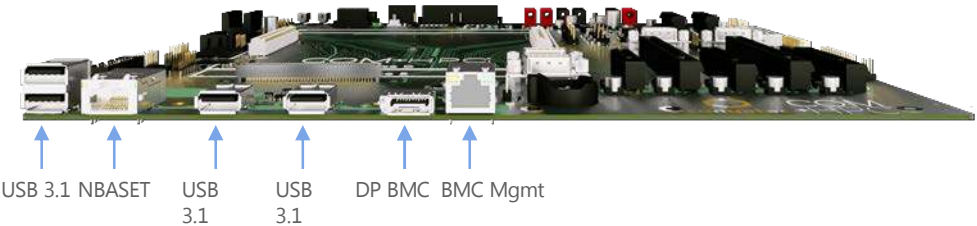
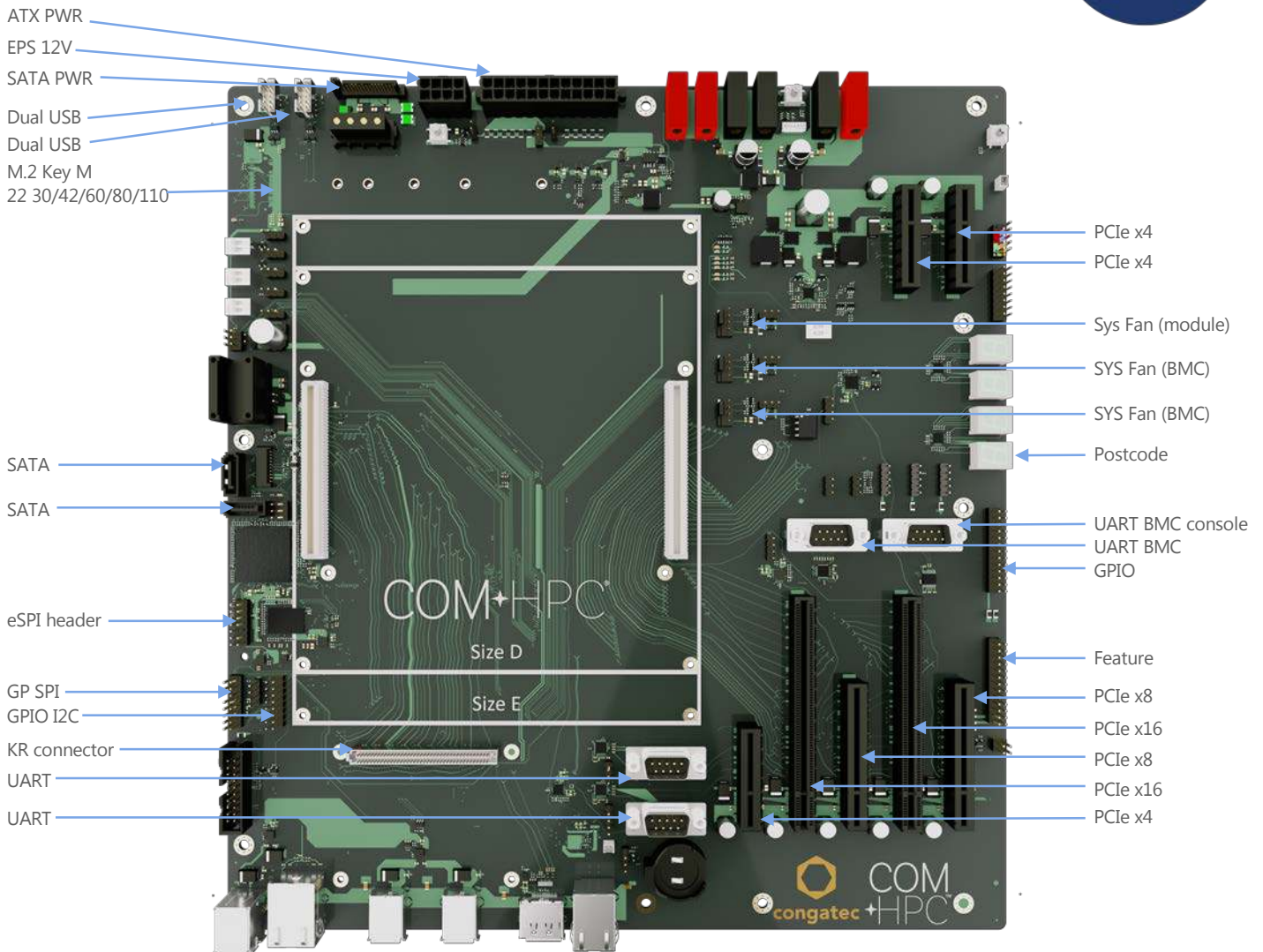
304.8 x 330.2 mm (approx. 12 x 13 inches)

Order Information

PN 065500 conga-HPC/EVAL-Server (Evaluation Carrier Board for COM-HPC Server type modules)
 PN 065505 conga-HPC/LEK-C827-IM 4SFP28 (COM-HPC Mezzanine card with Intel C827-IM, 4xSFP28)
 PN 065506 conga-HPC/LEK-XL827-AM 8SFP+ (COM-HPC Mezzanine card with 2x Intel XL827-AM, 8xSFP+)
 PN 065507 conga-HPC/LEK-QSFP (COM-HPC Mezzanine card with direct connection: 4x SFP28 and 1x QSFP adapter)



conga-HPC/sEVAL | Connections



conga-HPC/sEVAL | 10/25G Ethernet Mezzanine Cards



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